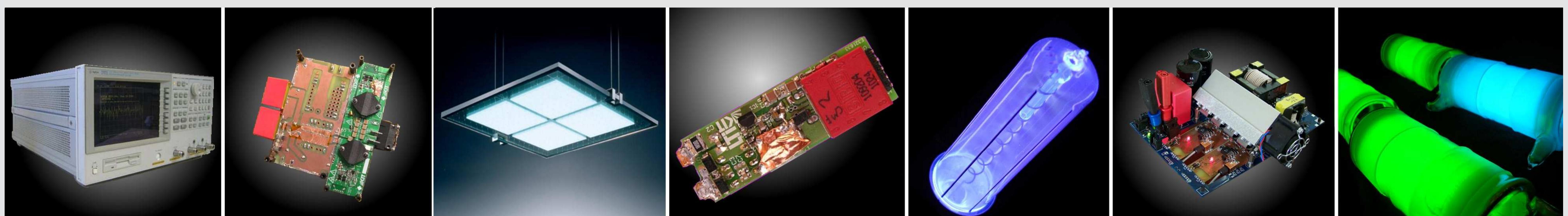


# Impedance Characterization of High-Frequency Gate Drive Circuits for Silicon RF MOSFET and Silicon-Carbide Field-Effect Transistors

Michael Meisser, Karsten Hähre

mail to: [michael.meisser@kit.edu](mailto:michael.meisser@kit.edu)



## Multi-MHz Half-Bridges – Ensuring Necessary RF Switching Performance

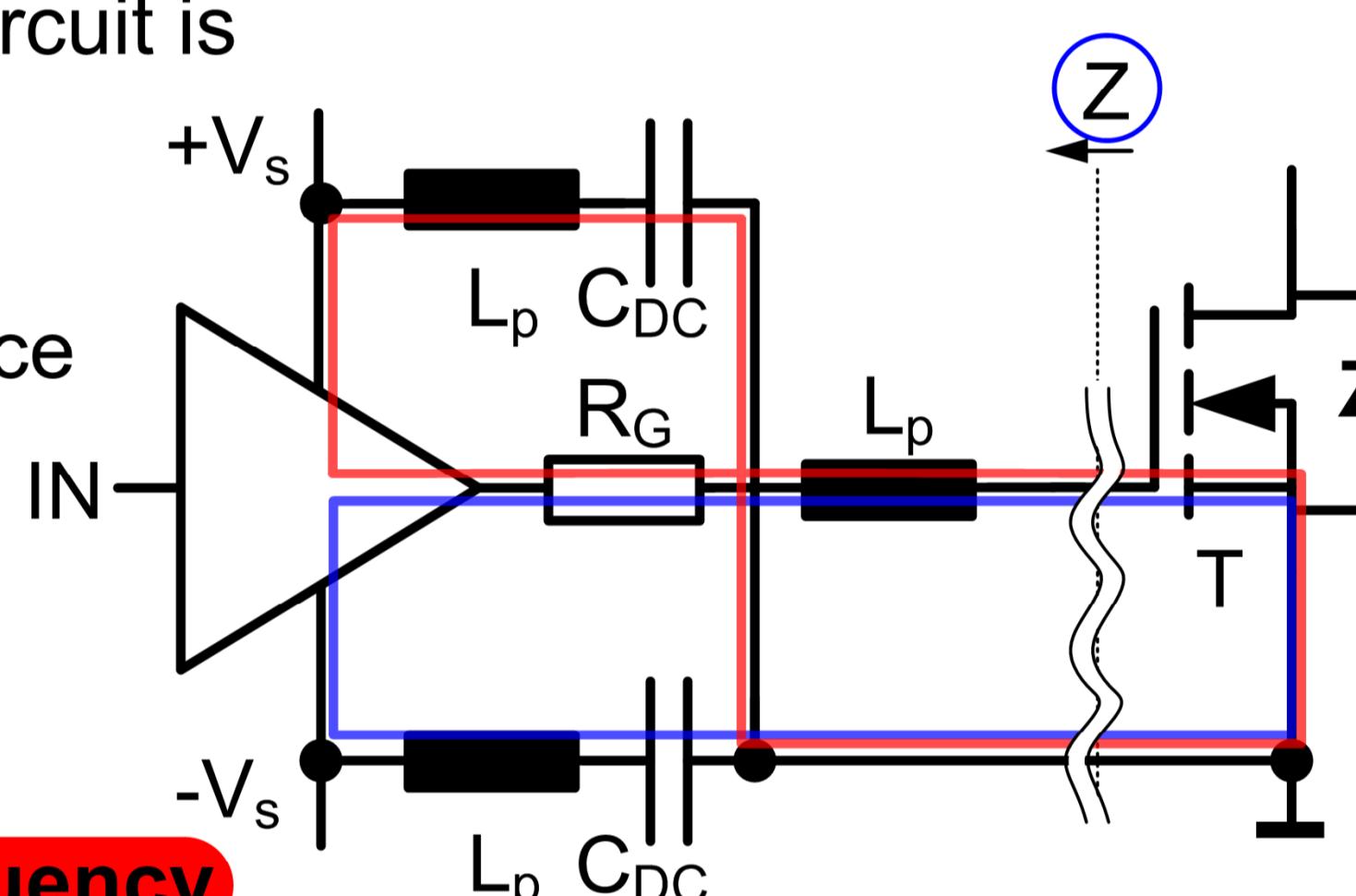
AC

### evaluating gate drive performance

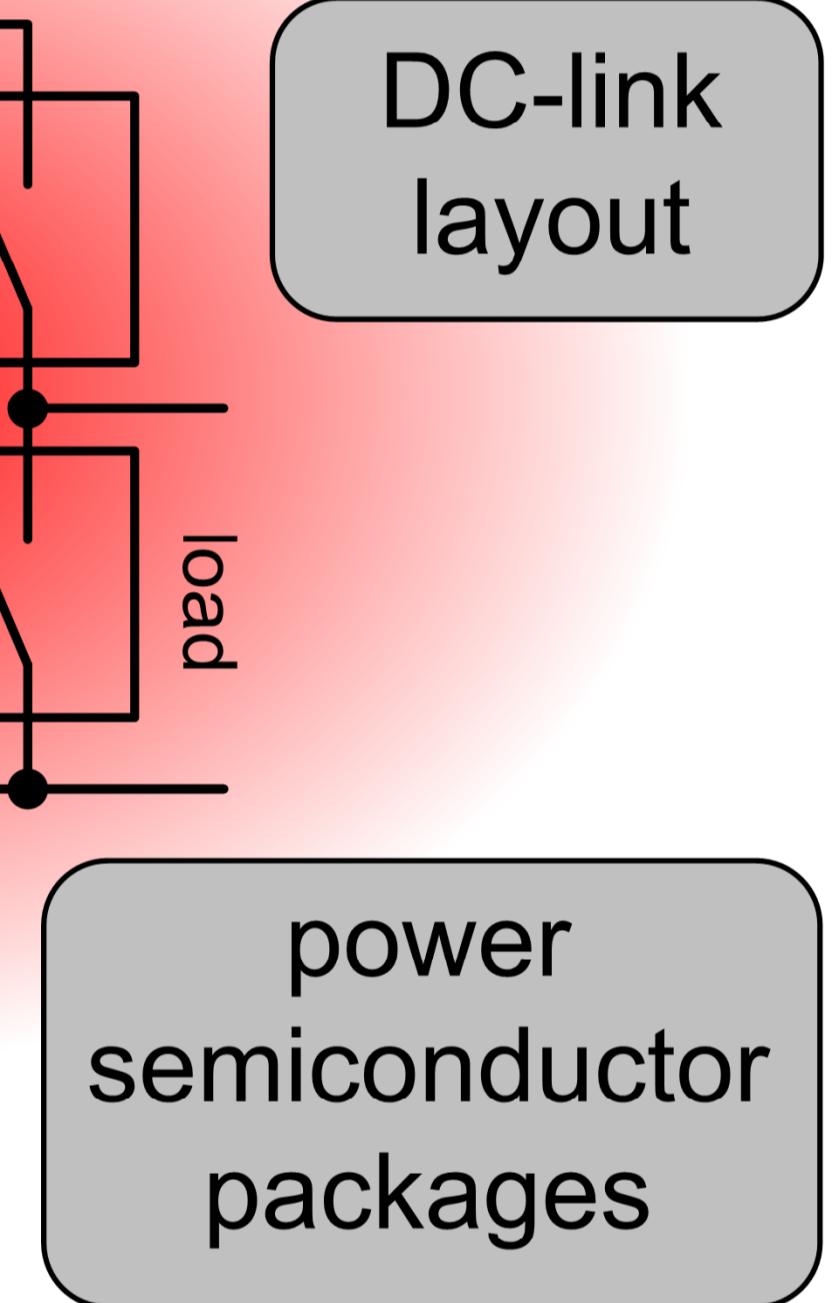
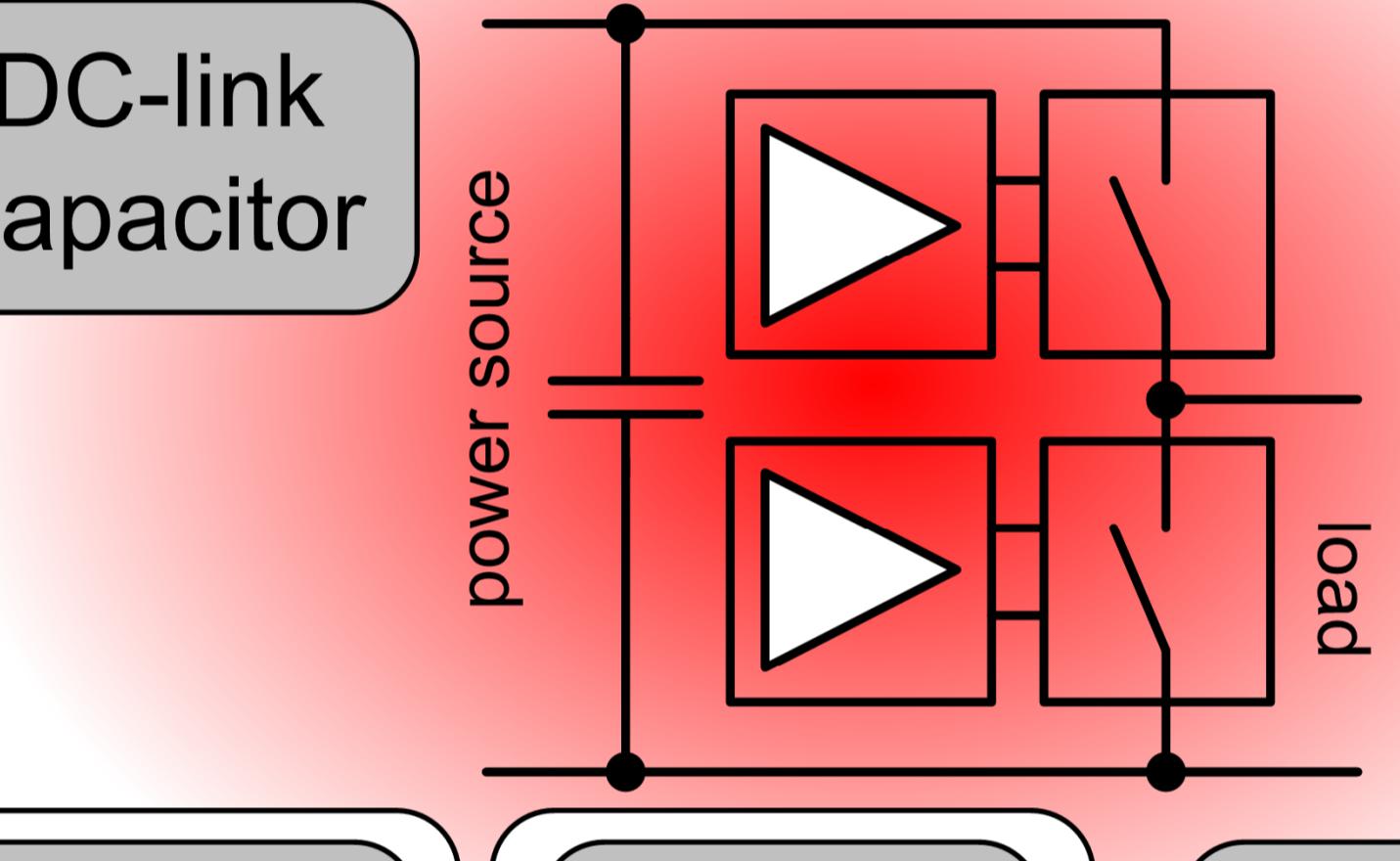
DC

### critical circuit parts

- because of parasitic inductance, RLC circuit is formed
- quality factor < 2 to prevent resonance
- low impedance at operation frequency for fast  $C_{GS}$  charge
- use impedance spectrum measurement to characterize resonance behavior
- perform measurement under DC-bias

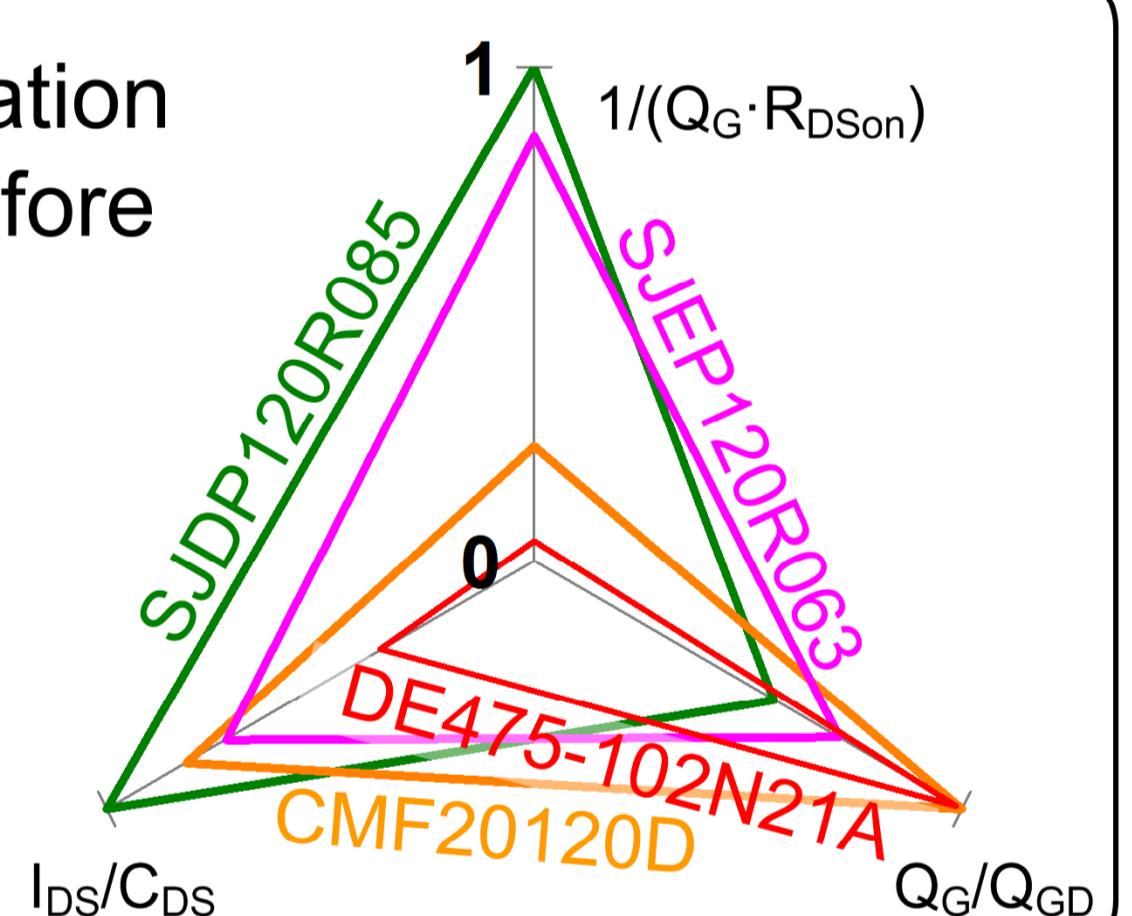


- static Voltage levels to be reached soon after switching
- low resistance at DC against Miller-feedback
- maximum gate resistance value restricted

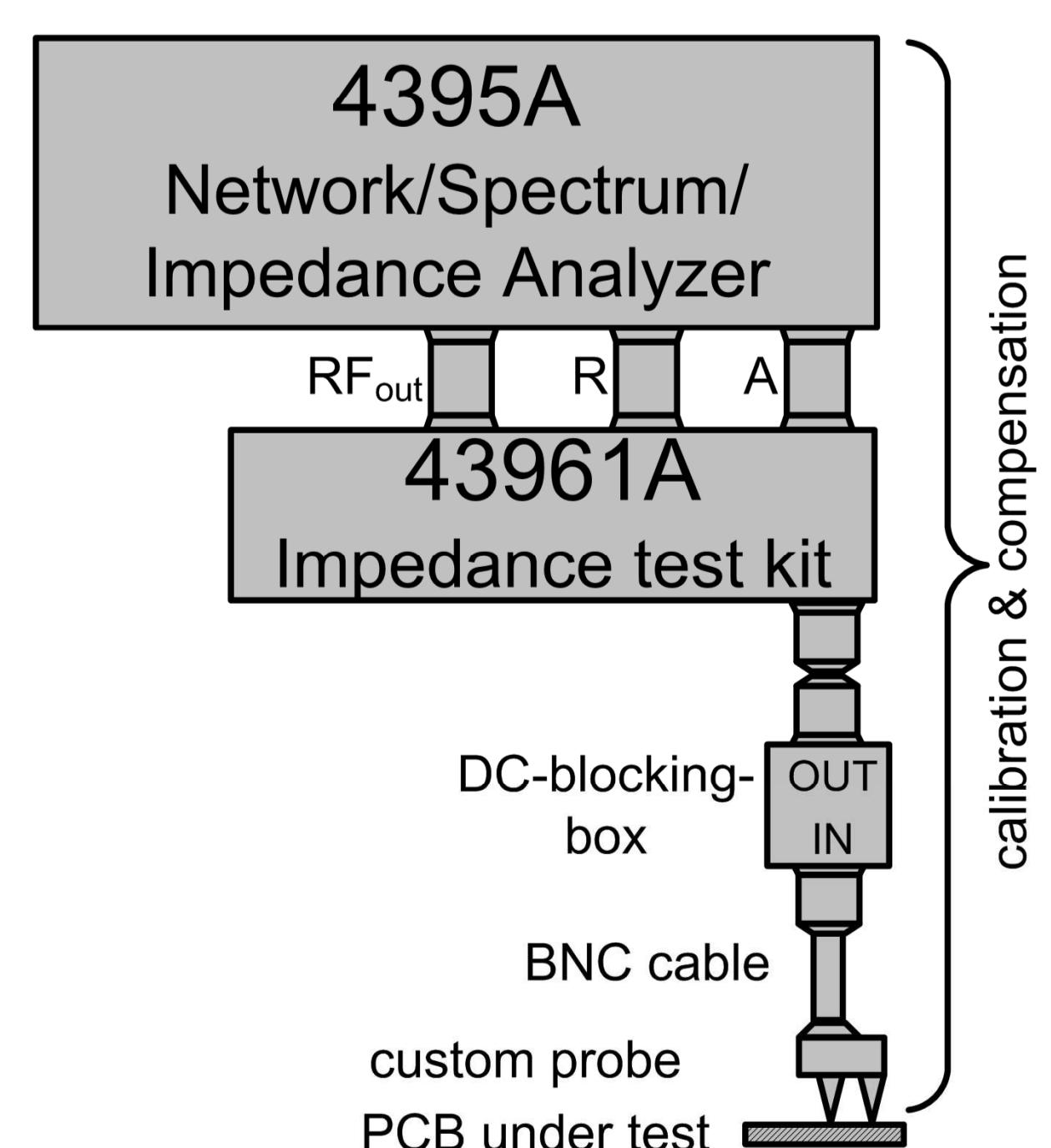
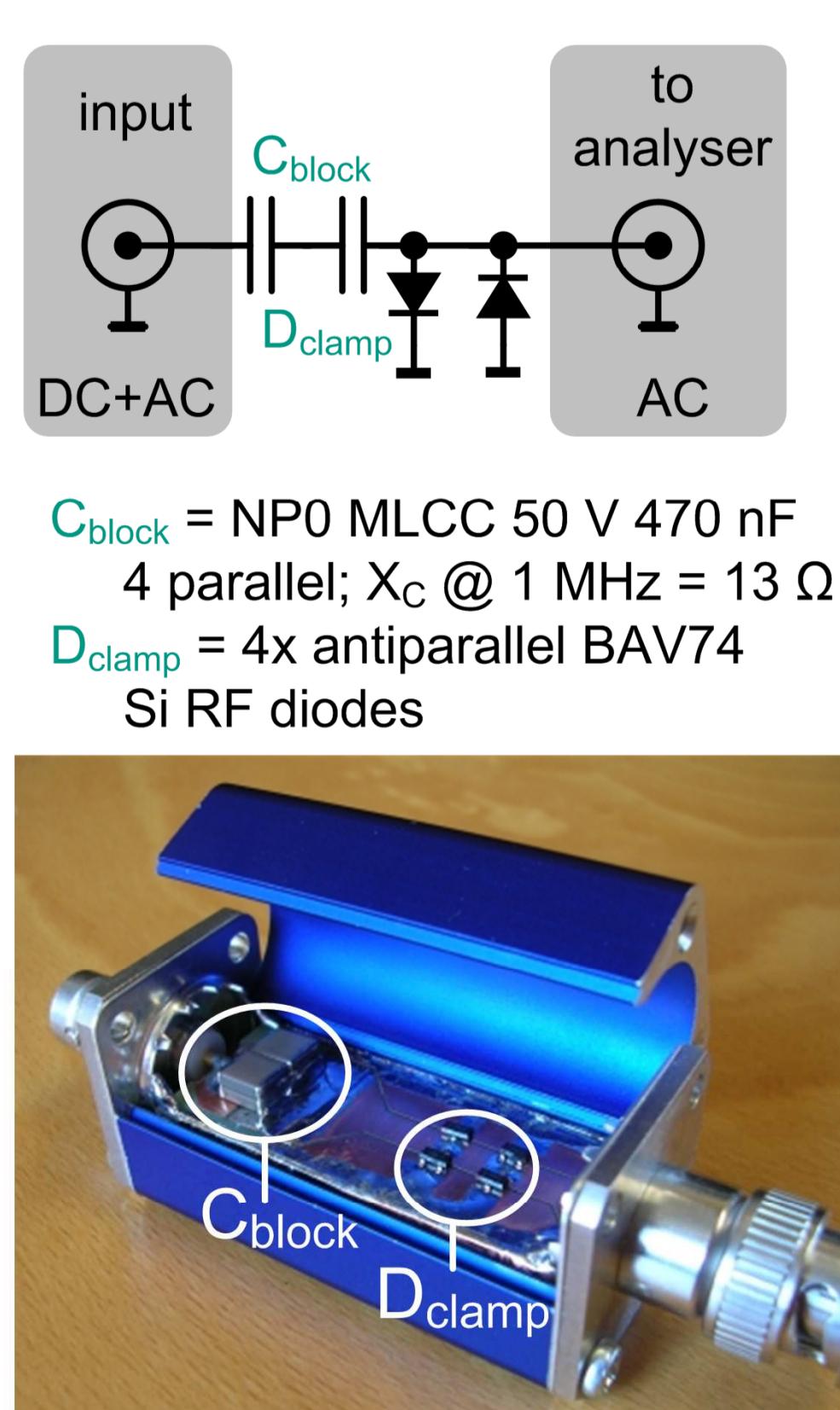


- Si and SiC MOSFETs offer high robustness needed for half-bridge configuration
- normally-on JFET is superior regarding FOM and maximum slew rate, therefore predestined for HF-application

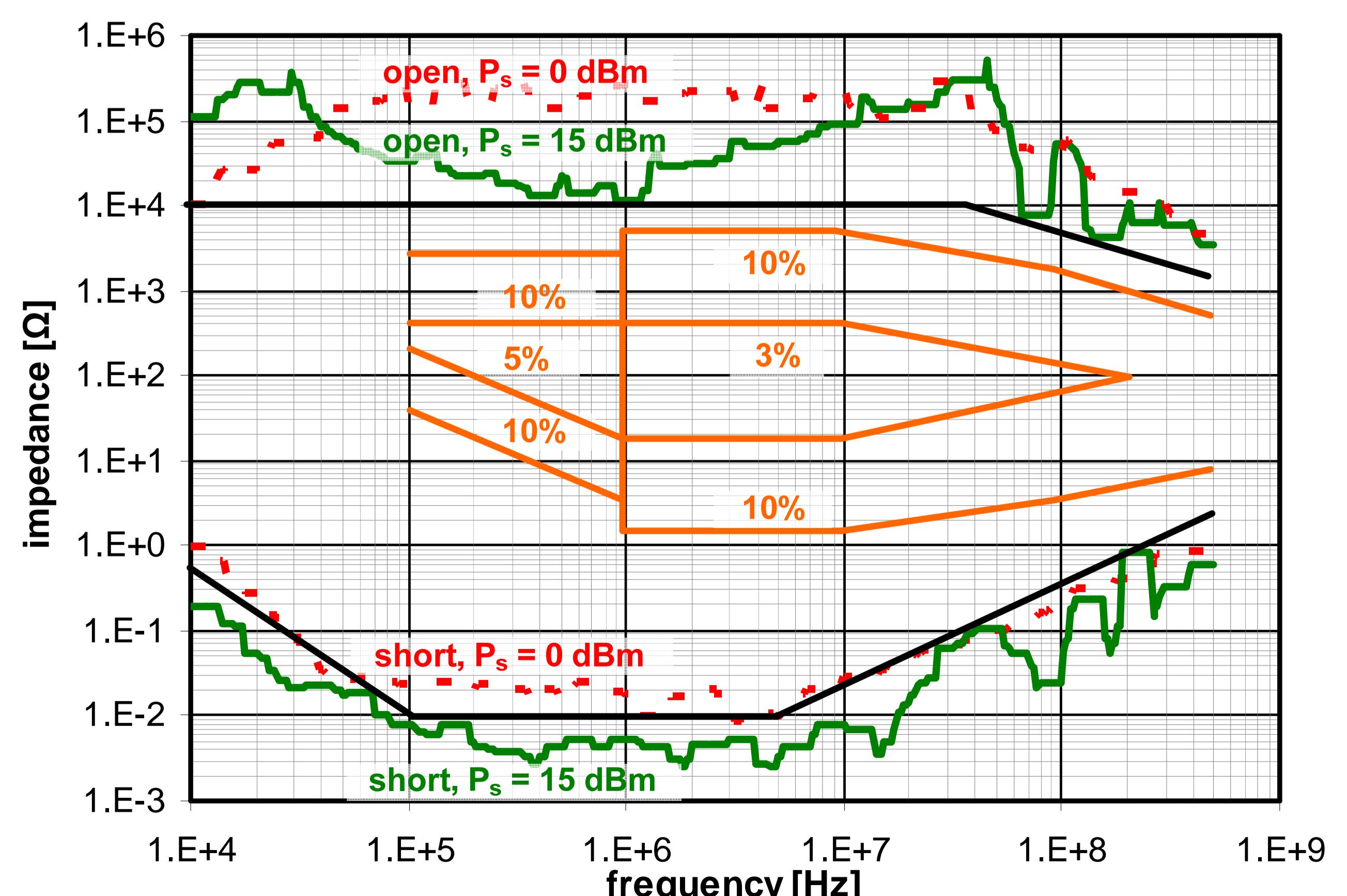
device	type	$V_{GS}$ [V]	$I_{DS}$ [A]	FOM $1/(Q_G \cdot R_{DSon})$	robustness $Q_G/Q_{GD}$	max. slew rate $I_{DS}/C_{DS}$ [V/ns]
DE475-102N21A	RF Si MOSFET	+15/-15	24	0.015	2.078	120
CMF20120D	SiC MOSFET	+25/-5	24	0.085	2.107	275
SJDP120R085	SiC n-on JFET	+15(+3)/-15	27	0.368	1.185	338
SJEP120R063	SiC n-off JFET	+15(+2)/-15	30	0.317	1.502	244



## Impedance Measurement under DC bias



## Measurement System Performance

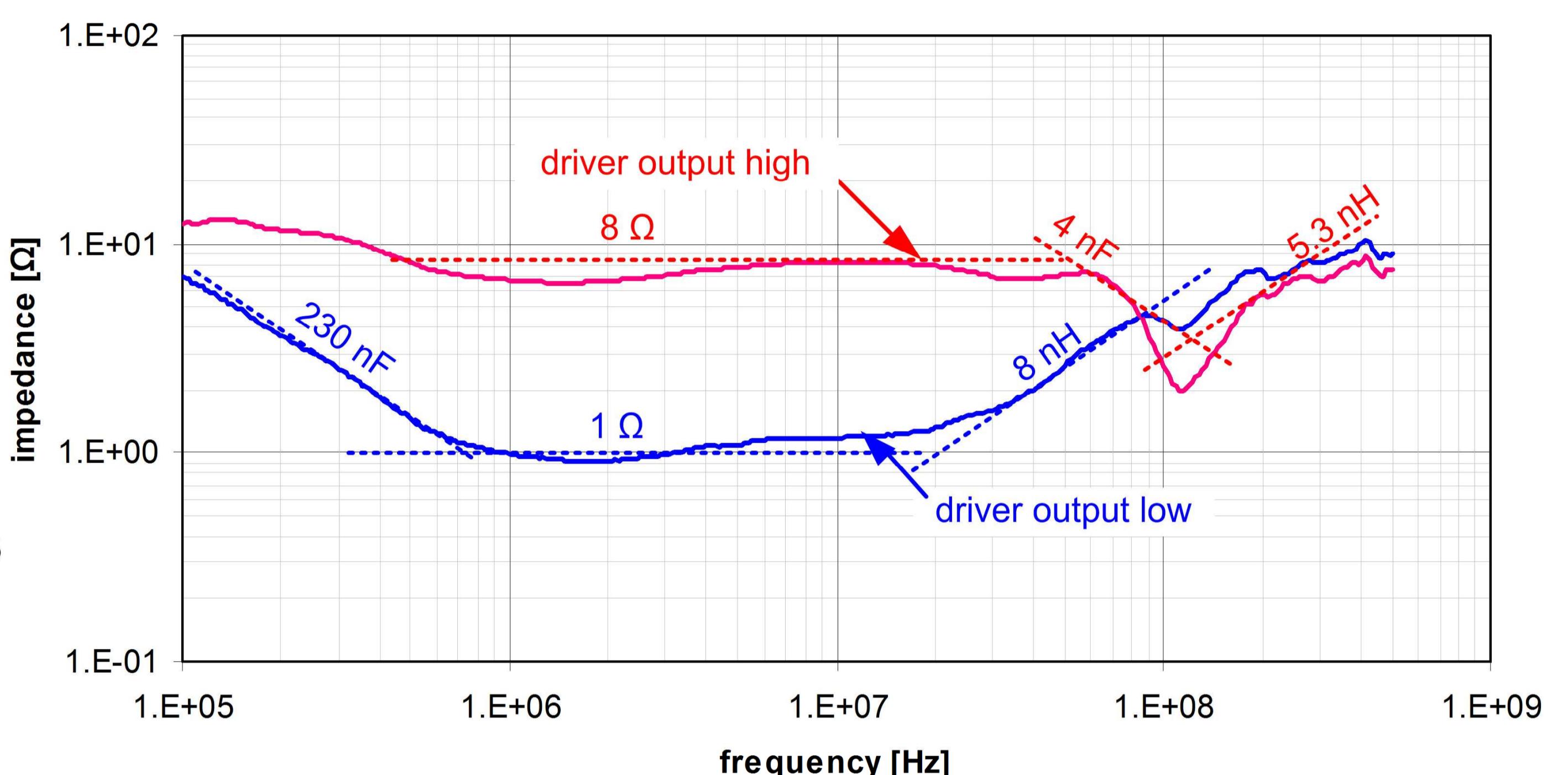
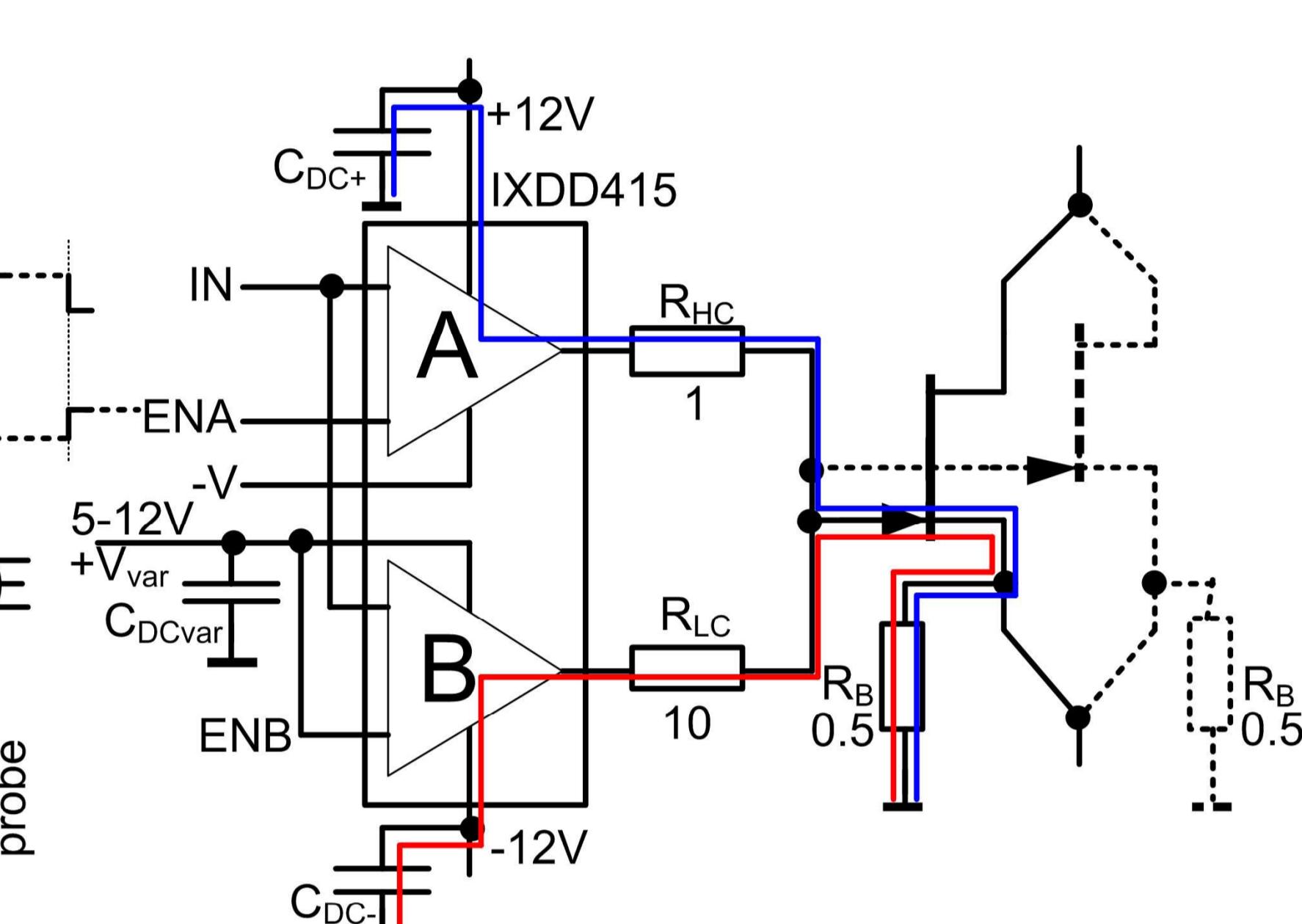
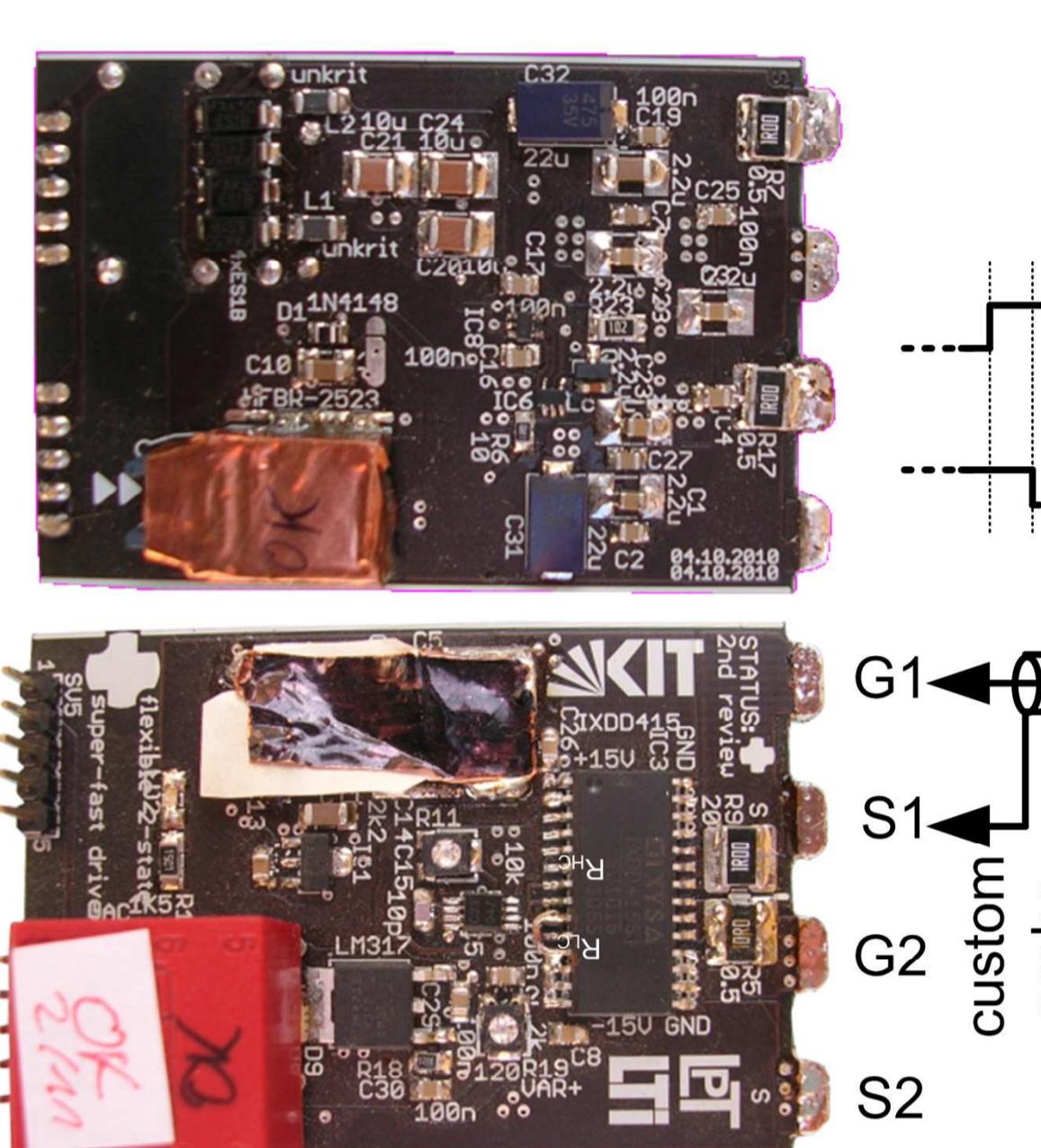


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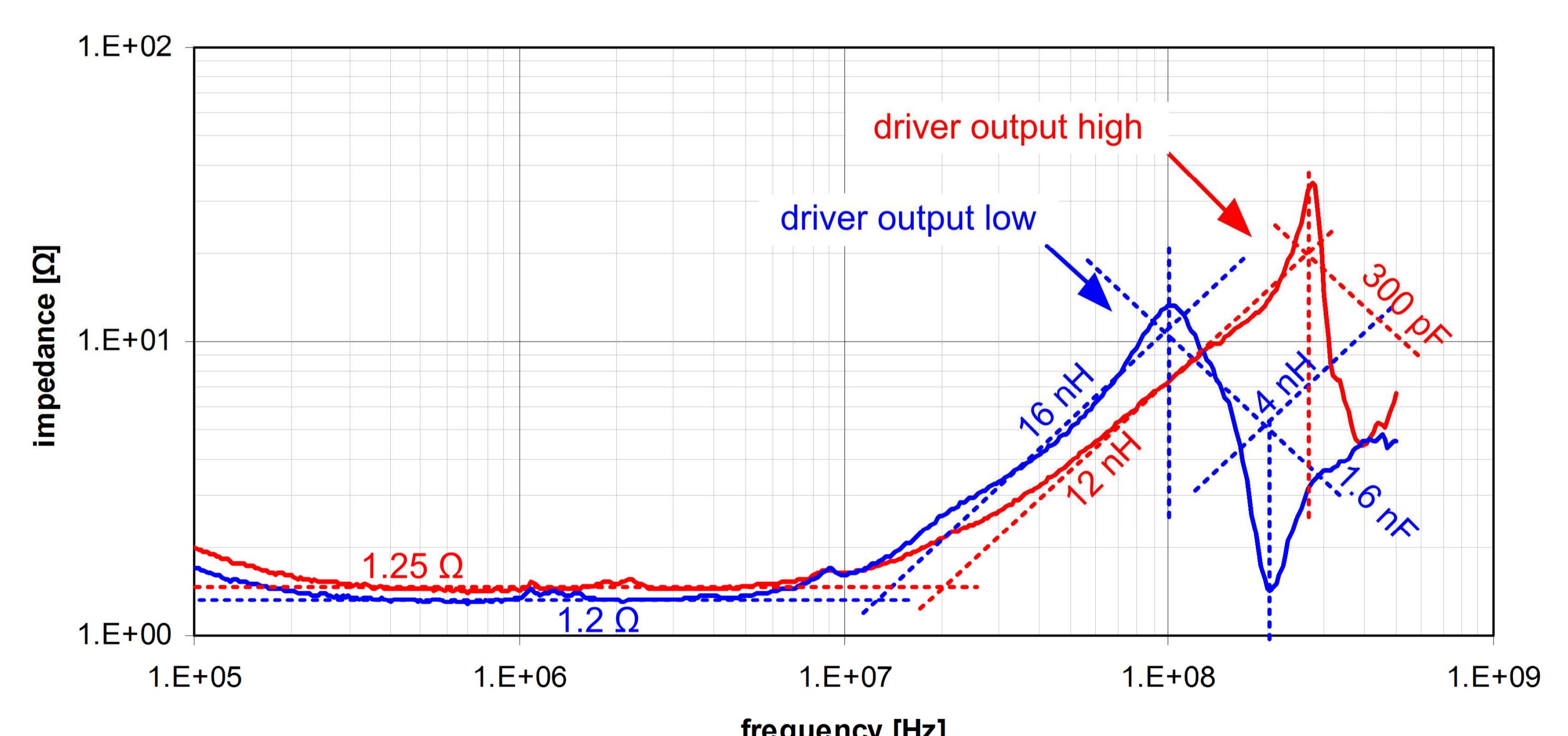
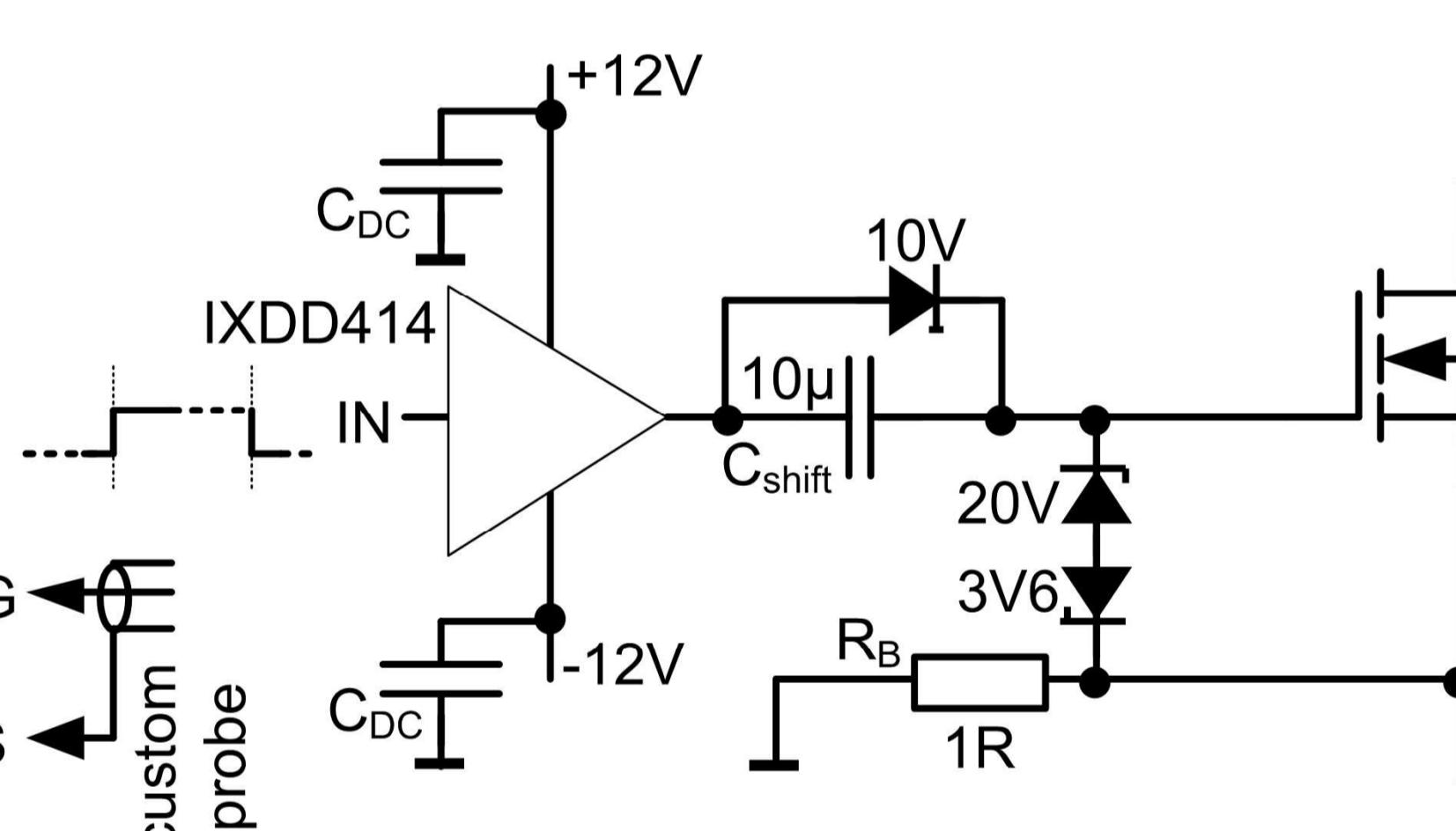
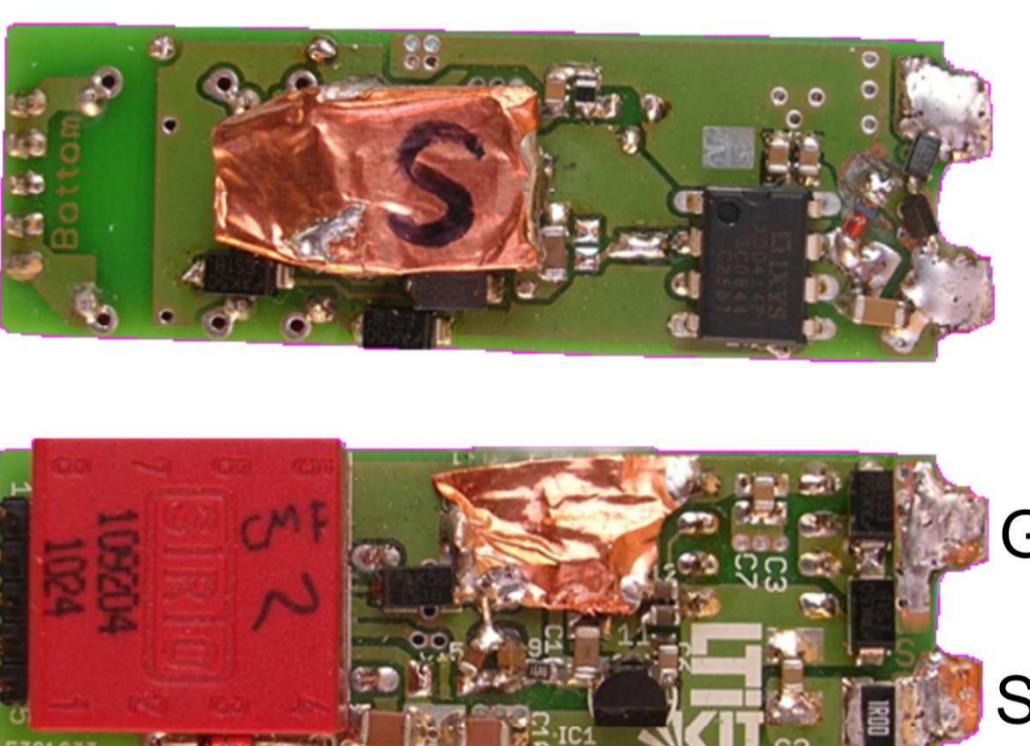
mail to: [michael.meisser@kit.edu](mailto:michael.meisser@kit.edu)

## SiC Normally-Off JFET Two-Current-Level Gate Driver Impedance Characterization



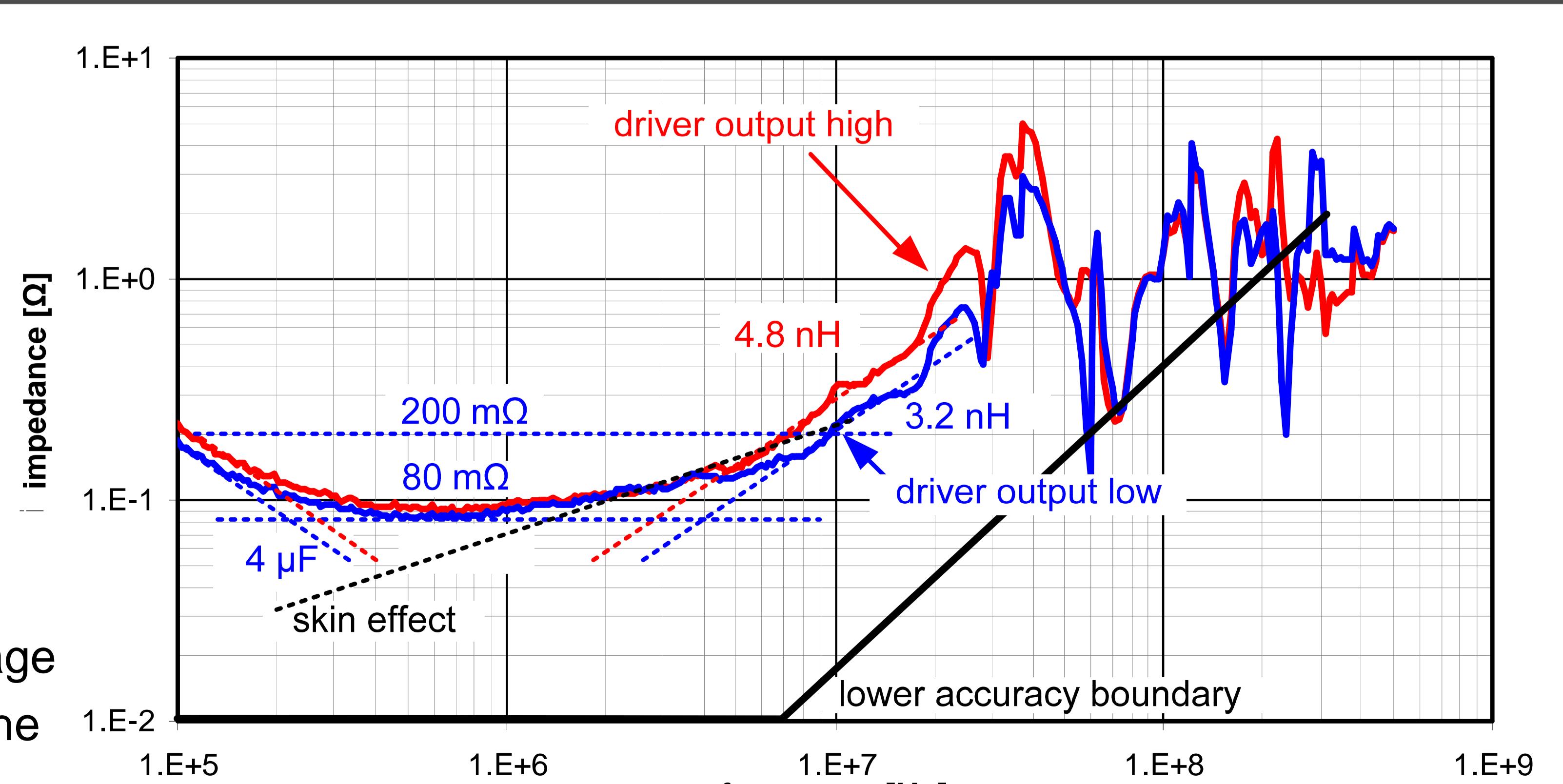
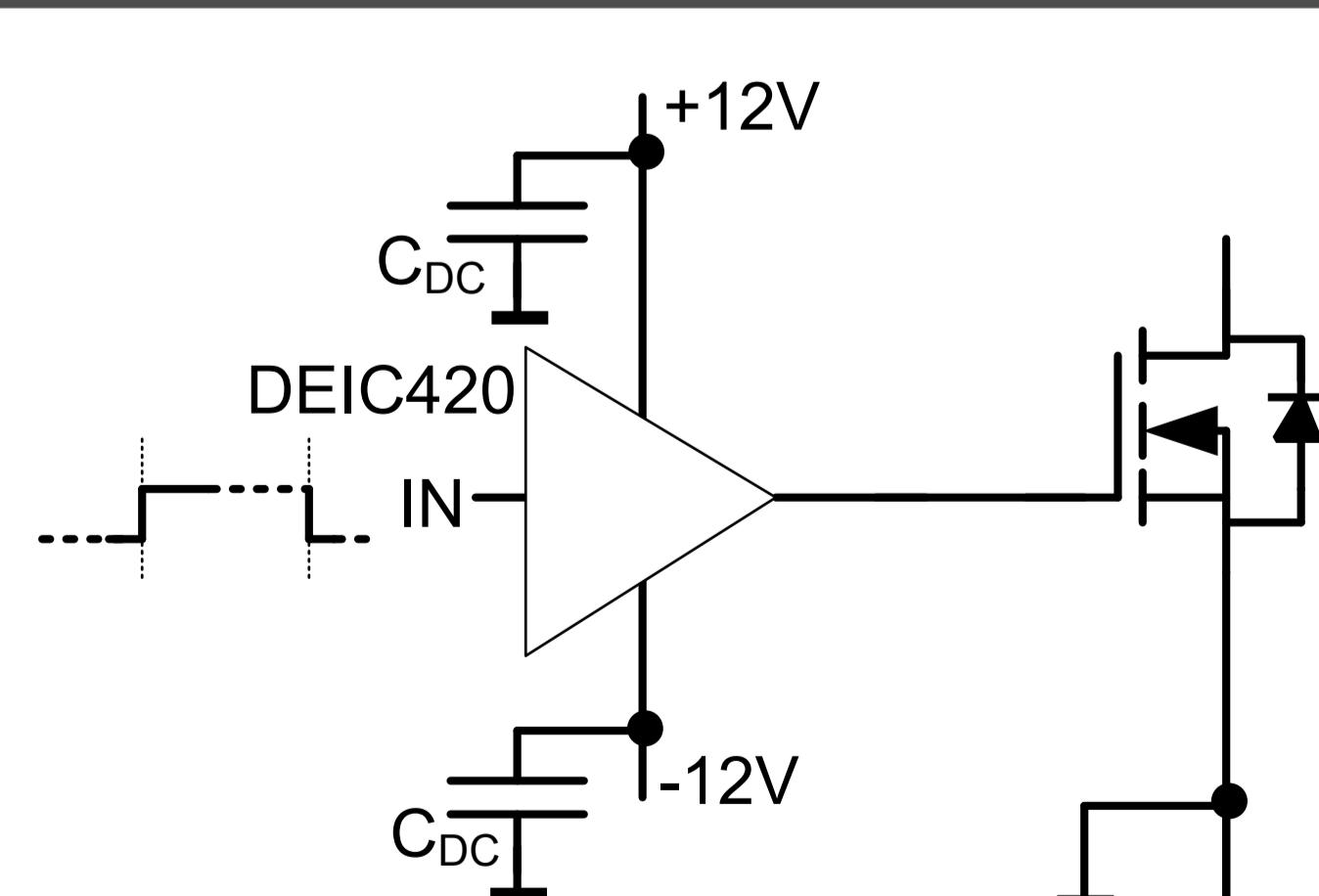
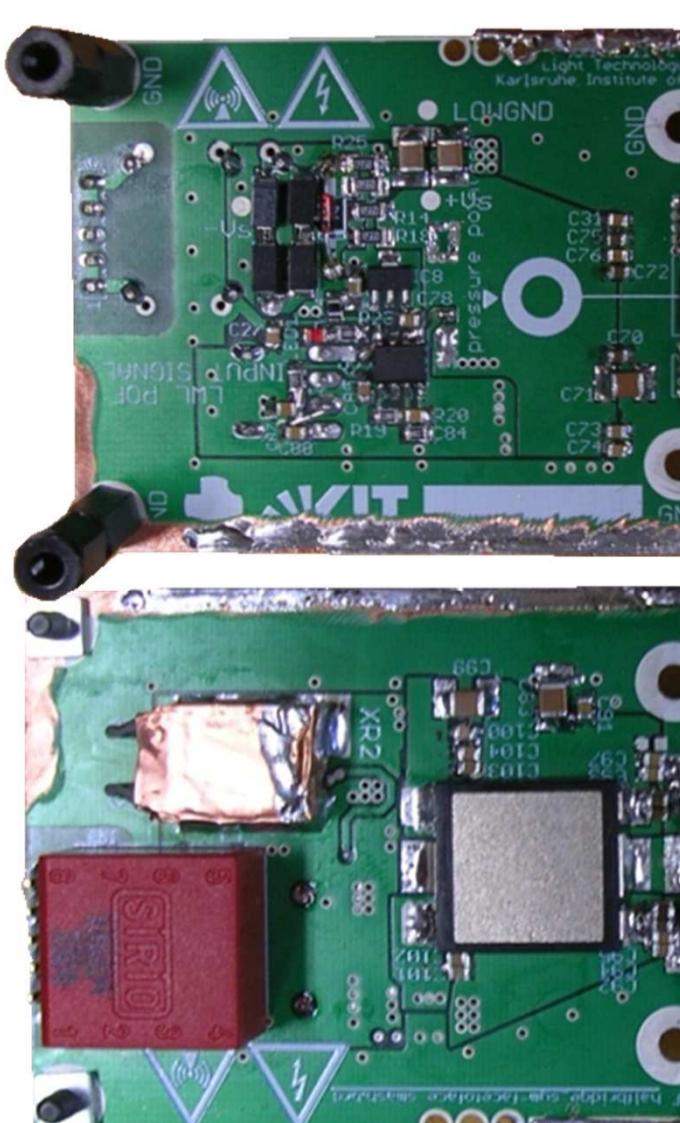
- comparatively low parasitic inductance due to RF-enhanced SOIC driver package
- different inductance values depending on current path
- too small DC bypass capacitor value

## SiC MOSFET Level-Shifting Gate Driver Impedance Characterization



- comparatively high parasitic inductance due to DIP driver package
- sufficient DC bypass capacitor value ensures target impedance

## Si RF MOSFET Symmetrically Supplied Gate Driver Impedance Characterization



- lowest parasitic inductance due to DEIC-RF driver package
- the lower the target impedance, the higher the value of the necessary DC bypass capacitors ➔ paralleling